

In The Claims

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Claim 1. (currently amended) An etching agent for etching copper in an etching process comprising an aqueous solution containing potassium hydrogen peroxomonosulfate, a concentration of said potassium hydrogen peroxomonosulfate falling within a range of ~~about~~ 10.01% to about 23.31% by weight of the etching agent, said etching agent etching the copper at an approximately uniform rate throughout the etching process.

Claim 2. (original) An etching agent for copper according to Claim 1, wherein said aqueous solution contains acetic acid.

Claim 16. (new) An etching agent according to claim 1, wherein said etching agent is capable of selectively etching the copper.